


Full Material Declaration for attached parts list

Report generated: 17 November 2025, 15:02 GMT

	Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -
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Declaration effective from: 02 January 2014 [Approved on 25 July 2025, 19:46 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.14%	Silicon	7440-21-3	100%
Die attach	Other nonferrous metals	0.57%	Formaldehyde, polymer with (chloromethyl)oxirane and phenol	9003-36-5	8.5%
Encapsulation	EP (Epoxy resin)	68.82%	Oxirane, [[4-(1,1-dimethylethyl)phenoxy]methyl]-	3101-60-8	10.2%
			Silver	7440-22-4	81.3%
			Carbon black	1333-86-4	0.3%
			ALUMINUM(III) HYDROXIDE	21645-51-2	1%
			phenolic epoxy resin	61788-97-4	5.7%
			Epoxy resin 89	26335-32-0	6%
Inner preparation	Copper alloys	0.07%	Quartz sand	60676-86-0	87%
Leadfinish	Tin plating	1.6%	COPPER, ELEMENTAL	7440-50-8	100%
Leadframe	Nickel and Nickel alloys	28.8%	Tin elemental	7440-31-5	100%
			Copper	7440-50-8	0.2%
			SILVER, ELEMENTAL	7440-22-4	1.2%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.6%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-23/TO-236_Pb&H-free_(H)	Diode/Transistor SMD	0.01	g